

V <sub>CES</sub>	650V
I <sub>C(100°C)</sub>	19A
V <sub>CE(sat) (Typ.)</sub>	1.6V@I <sub>C</sub> =40A
P <sub>D</sub>	66W

#### Features

- 1) Low Collector Emitter Saturation Voltage
- 2) High Speed Switching
- 3) Low Switching Loss & Soft Switching
- Built in Very Fast & Soft Recovery FRD (RFN - Series)
- 5) Pb free Lead Plating ; RoHS Compliant

#### Applications

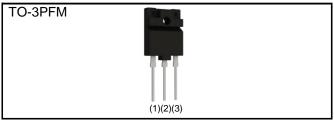
PFC

UPS

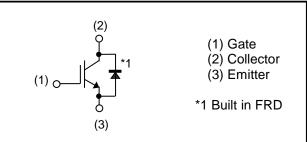
**Power Conditioner** 

IH

#### Outline



#### Inner Circuit



#### Packaging Specifications

	Packaging	Tube
	Reel Size (mm)	-
Tupo	Tape Width (mm)	-
Туре	Basic Ordering Unit (pcs)	450
	Packing Code	C11
	Marking	RGTH80TK65D

#### ●Absolute Maximum Ratings (at T<sub>C</sub> = 25°C unless otherwise specified)

	,					
Parameter		Symbol	Value	Unit		
Collector - Emitter Voltage		V <sub>CES</sub>	650	V		
Gate - Emitter Voltage		V <sub>GES</sub>	±30	V		
Collector Current	$T_{\rm C} = 25^{\circ}{\rm C}$	Ι <sub>C</sub>	31	А		
Collector Current	$T_{\rm C} = 100^{\circ}{\rm C}$	Ι <sub>C</sub>	19	А		
Pulsed Collector Current		I <sub>CP</sub> *1	160	А		
Diode Forward Current	$T_{\rm C} = 25^{\circ}{\rm C}$	١ <sub>F</sub>	28	А		
Diode Forward Current	$T_{\rm C} = 100^{\circ}{\rm C}$	l <sub>F</sub>	16	А		
Diode Pulsed Forward Current		I <sub>FP</sub> <sup>*1</sup>	160	А		
Power Dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	P <sub>D</sub>	66	W		
Power Dissipation	$T_{C} = 100^{\circ}C$	P <sub>D</sub>	33	W		
Operating Junction Temperatu	re	Tj	-40 to +175	°C		
Storage Temperature		T <sub>stg</sub>	-55 to +175	°C		
*1 Pulse width limited by T		-	-			

\*1 Pulse width limited by T<sub>jmax.</sub>

#### Thermal Resistance

Parameter	Symbol	Values			Unit
Parameter	Symbol	Min.	Тур.	Max.	Offic
Thermal Resistance IGBT Junction - Case	$R_{\theta(j\text{-}c)}$	-	-	2.27	°C/W
Thermal Resistance Diode Junction - Case	$R_{\theta(j\text{-}c)}$	-	-	3.76	°C/W

### •IGBT Electrical Characteristics (at $T_j = 25^{\circ}C$ unless otherwise specified)

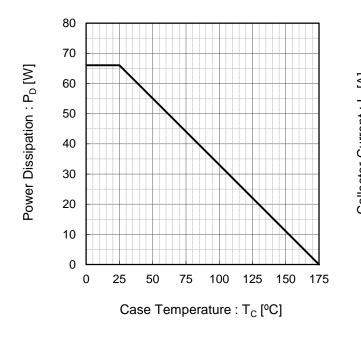
Parameter	Symbol	Conditions	Values			Unit	
Farameter	Symbol	ymbol Conditions -		Тур.	Max.	Unit	
Collector - Emitter Breakdown Voltage	BV <sub>CES</sub>	I <sub>C</sub> = 10μΑ, V <sub>GE</sub> = 0V	650	-	-	V	
Collector Cut - off Current	I <sub>CES</sub>	V <sub>CE</sub> = 650V, V <sub>GE</sub> = 0V	-	-	10	μA	
Gate - Emitter Leakage Current	I <sub>GES</sub>	$V_{GE}$ = ±30V, $V_{CE}$ = 0V	-	-	±200	nA	
Gate - Emitter Threshold Voltage	V <sub>GE(th)</sub>	V <sub>CE</sub> = 5V, I <sub>C</sub> = 27.6mA	4.5	5.5	6.5	V	
Collector - Emitter Saturation Voltage	V <sub>CE(sat)</sub>	$I_{C} = 40A, V_{GE} = 15V$ $T_{j} = 25^{\circ}C$ $T_{j} = 175^{\circ}C$	-	1.6 2.1	2.1 -	V	

## •IGBT Electrical Characteristics (at $T_j = 25^{\circ}C$ unless otherwise specified)

Deremeter	Symbol	Conditions	Values			l la it	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input Capacitance	$C_{ies}$	V <sub>CE</sub> = 30V	-	2210	-		
Output Capacitance	C <sub>oes</sub>	$V_{GE} = 0V$	-	85	-	pF	
Reverse Transfer Capacitance	C <sub>res</sub>	f = 1MHz	-	35	-		
Total Gate Charge	$Q_g$	V <sub>CE</sub> = 300V	-	79	-		
Gate - Emitter Charge	$Q_{ge}$	I <sub>C</sub> = 40A	-	21	-	nC	
Gate - Collector Charge	$Q_{gc}$	V <sub>GE</sub> = 15V	-	29	-		
Turn - on Delay Time	t <sub>d(on)</sub>	$I_{\rm C} = 40$ A, $V_{\rm CC} = 400$ V	-	34	-		
Rise Time	t <sub>r</sub>	$V_{GE} = 15V, R_G = 10\Omega$	-	50	-		
Turn - off Delay Time	t <sub>d(off)</sub>	$T_j = 25^{\circ}C$	-	120	-	ns	
Fall Time	t <sub>f</sub>	Inductive Load	-	47	-		
Turn - on Delay Time	t <sub>d(on)</sub>	$I_{\rm C} = 40$ A, $V_{\rm CC} = 400$ V	-	34	-		
Rise Time	t <sub>r</sub>	$V_{GE} = 15V, R_{G} = 10\Omega$	-	50	-		
Turn - off Delay Time	t <sub>d(off)</sub>	T <sub>j</sub> = 175°C	-	135	-	ns	
Fall Time	t <sub>f</sub>	Inductive Load	-	59	-		
		$I_{\rm C} = 160$ A, $V_{\rm CC} = 520$ V					
Reverse Bias Safe Operating Area	RBSOA	V <sub>P</sub> = 650V, V <sub>GE</sub> = 15V	FU	LL SQUA	RE	-	
		R <sub>G</sub> = 60Ω, T <sub>j</sub> = 175°C					

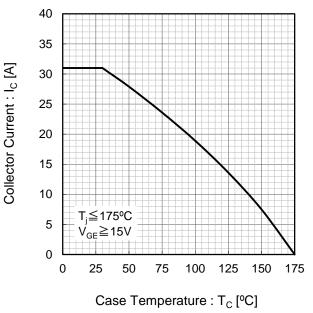
# •FRD Electrical Characteristics (at $T_j = 25^{\circ}C$ unless otherwise specified)

Deremeter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Diode Forward Voltage	V <sub>F</sub>	$I_F = 20A$ $T_j = 25^{\circ}C$ $T_j = 175^{\circ}C$	-	1.35 1.15	1.8 -	V
Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20A	-	58	-	ns
Diode Peak Reverse Recovery Current	I <sub>rr</sub>	V <sub>CC</sub> = 400V di <sub>F</sub> /dt = 200A/µs	-	6.5	-	А
Diode Reverse Recovery Charge	Q <sub>rr</sub>	T <sub>j</sub> = 25°C	-	0.21	-	μC
Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20A	-	236	-	ns
Diode Peak Reverse Recovery Current	I <sub>rr</sub>	V <sub>CC</sub> = 400V di <sub>F</sub> /dt = 200A/µs	-	10.7	-	А
Diode Reverse Recovery Charge	Q <sub>rr</sub>	T <sub>j</sub> = 175°C	-	1.36	-	μC



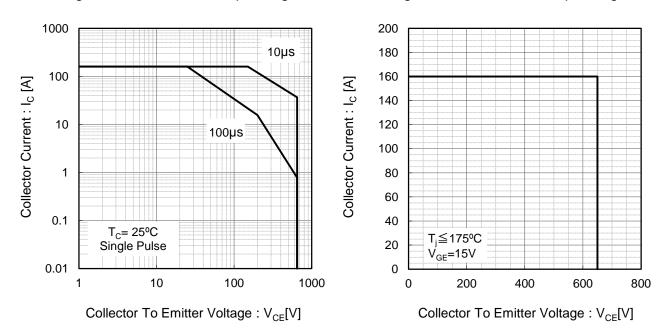
#### Fig.1 Power Dissipation vs. Case Temperature

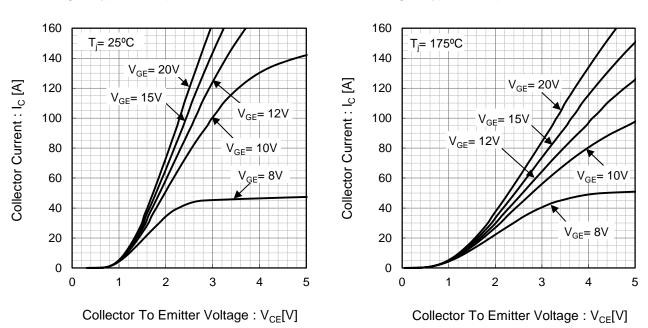
Fig.2 Collector Current vs. Case Temperature



#### Fig.3 Forward Bias Safe Operating Area

Fig.4 Reverse Bias Safe Operating Area

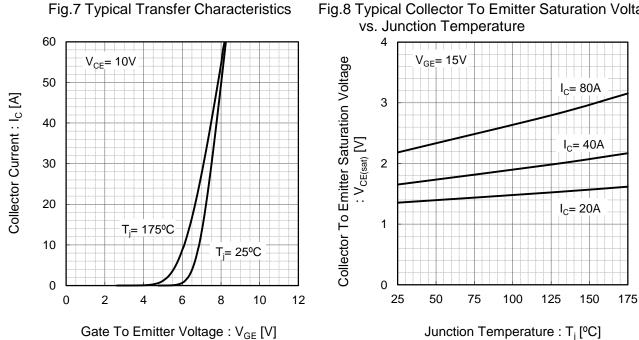




#### Fig.5 Typical Output Characteristics

# Fig.8 Typical Collector To Emitter Saturation Voltage

Fig.6 Typical Output Characteristics



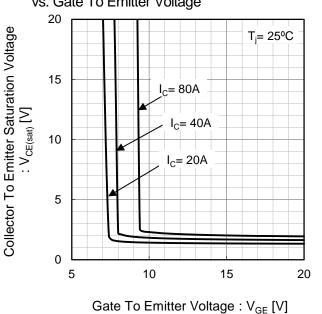
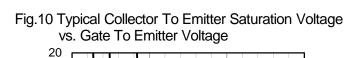
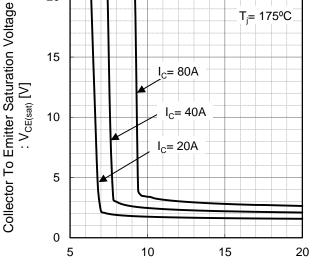
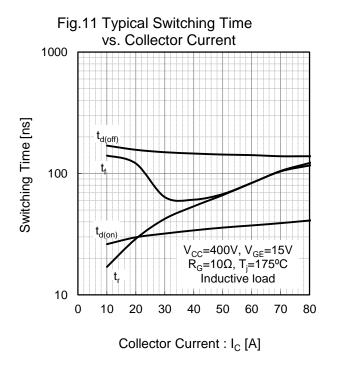


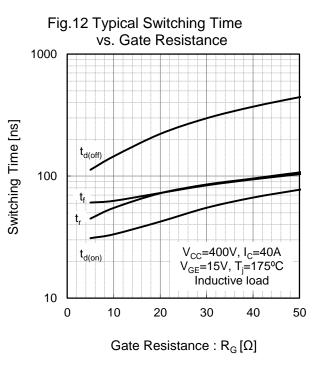
Fig.9 Typical Collector To Emitter Saturation Voltage vs. Gate To Emitter Voltage

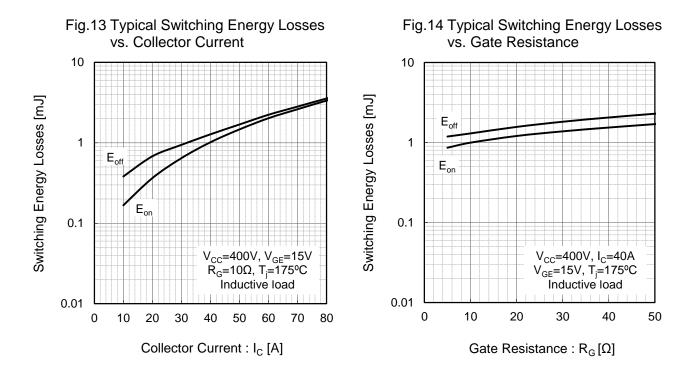


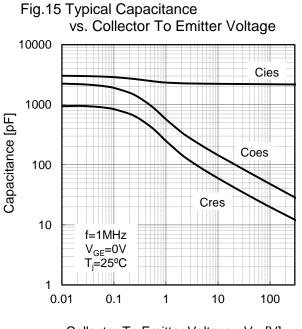


Gate To Emitter Voltage : V<sub>GE</sub> [V]



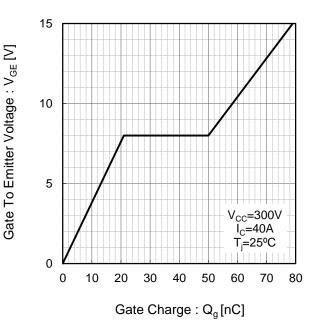


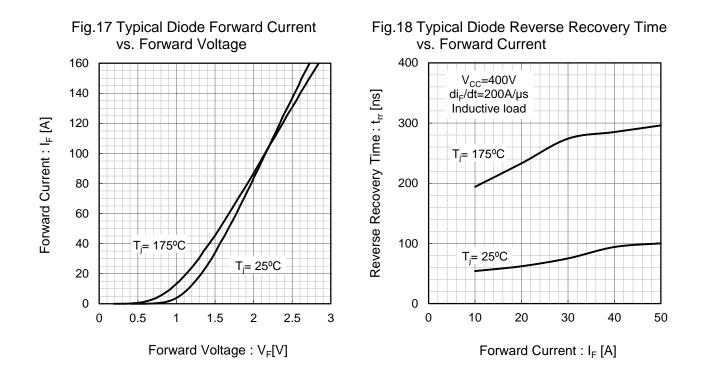




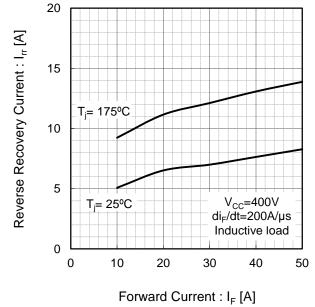
Collector To Emitter Voltage : V<sub>CE</sub>[V]

Fig.16 Typical Gate Charge

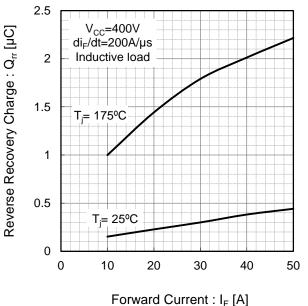




# Fig.19 Typical Diode Reverse Recovery Current vs. Forward Current



# Fig.20 Typical Diode Reverse Recovery Charge vs. Forward Current



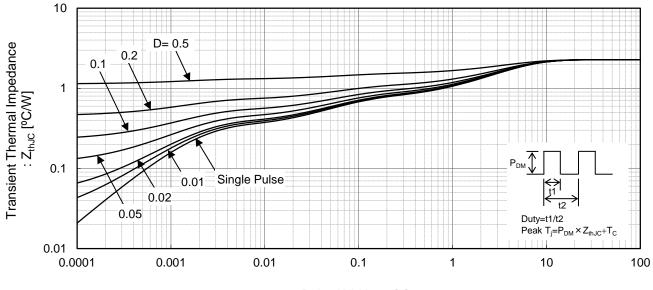


Fig.21 IGBT Transient Thermal Impedance

Pulse Width : t1[s]

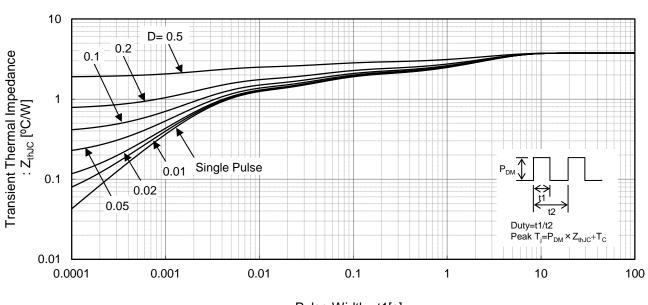


Fig.22 Diode Transient Thermal Impedance

Pulse Width : t1[s]

### ●Inductive Load Switching Circuit and Waveform

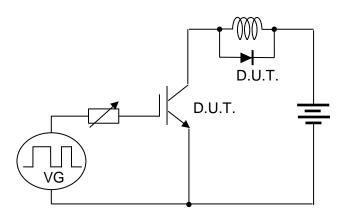


Fig.23 Inductive Load Circuit

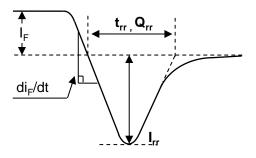
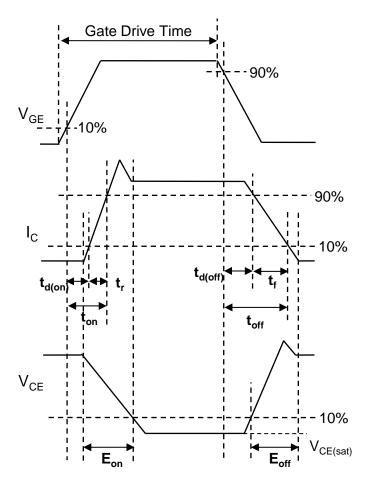
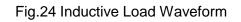


Fig.25 Diode Reverce Recovery Waveform





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